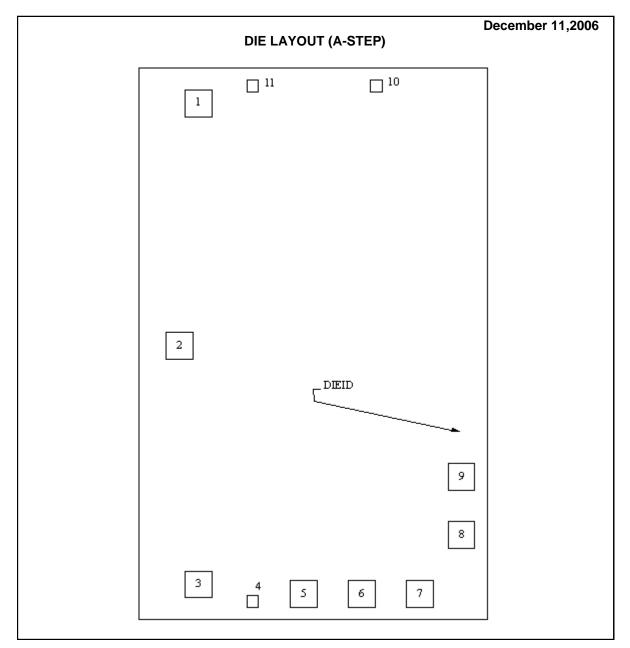


LM4701 MDC MWC OVERTURE™ AUDIO POWER AMPLIFIER SERIES 30W AUDIO POWER AMPLIFIER WITH MUTE AND STANDBY MODES



DIE/WAFER CHARACTERISTICS

Fabrication Attributes		General Die Information		
Physical Die Identification	LM1876A	Bond Pad Opening Size (min)	180μm x 180μm	
Die Step	A	Bond Pad Metalization	ALUMINUM	
Physical Attributes		Passivation	VOM NITRIDE	
Wafer Diameter	150mm	Back Side Metal	TITANIUM_NICKLE_SILVER BACKED	
Die Size (Drawn)	2337μm x 3708μm 92.0mils x 146.0mils	Back Side Connection	VEE	
Thickness	330μm Nominal			
Min Pitch	389µm Nominal			

Special Assembly Requirements:	
Note: Actual die size is rounded to the nearest micron.	



The Sight & Sound of Information LM4701 MDC MWC

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	Die Bond Pad Coordinate Locations (A -Step)							
(Referenced	(Referenced to die center, coordinates in μ m) NC = No Connection, N.U. = Not Used							
SIGNAL	PAD#	X/Y COORDINATES			SIZE			
NAME	NUMBER	Х	Y	X		Υ		
VCC	1	-770	1617	180	х	180		
OUTPUT	2	-900	-13	180	х	180		
VEE	3	-770	-1617	180	х	180		
NC	4	-407	-1732	80	x	80		
GND	5	-65	-1682	180	х	180		
MUTE	6	325	-1682	180	х	180		
VIN -	7	715	-1682	180	х	180		
VIN +	8	996	-1284	180	х	180		
STANDBY	9	996	-894	180	х	180		
NC	10	421	1732	80	x	80		
NC	11	-407	1732	80	Х	80		



DPBU Die Datasheet

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